

Material Content Data Sheet

RoHS

Sales Product Name	BTS612N1 E3128A	**Issued**	14. May 2021
MA#	MA003365844		
Package	PG-TO263-7-2	**Weight***	1508.16 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.579	0.30	0.30	3036	3036
leadframe	inorganic material	phosphorus	7723-14-0	0.241	0.02		160	
	non noble metal	iron	7439-89-6	0.803	0.05		532	
	non noble metal	copper	7440-50-8	801.714	53.15	53.22	531584	532276
wire	non noble metal	aluminium	7429-90-5	2.221	0.15	0.15	1472	1472
encapsulation	organic material	carbon black	1333-86-4	6.335	0.42		4201	
	inorganic material	antimonytrioxide	1309-64-4	13.246	0.88		8783	
	plastics	brominated resin	-	14.974	0.99		9929	
	plastics	epoxy resin	-	109.424	7.26		72555	
	inorganic material	silicondioxide	60676-86-0	431.937	28.64	38.19	286400	381868
leadfinish	non noble metal	tin	7440-31-5	12.317	0.82	0.82	8167	8167
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.269	0.02	0.02	179	180
solder	non noble metal	tin	7440-31-5	0.075			50	
	noble metal	silver	7440-22-4	0.094	0.01		62	
	non noble metal	lead	7439-92-1	3.579	0.24	0.25	2373	2485
heatspreader	inorganic material	phosphorus	7723-14-0	0.032			21	
	non noble metal	iron	7439-89-6	0.106	0.01		71	
	non noble metal	copper	7440-50-8	106.210	7.04	7.05	70424	70516
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com